

**Abstract**

The invention concerns a method for making a card with tips for testing semiconductor chips with microsphere bond pads. A first adhesive coat is vacuum deposited on a flexible polyimide film, followed by a second metal coat. A combination of UV photolithography and electroforming of a metal material enables to obtain the implantation of the tips. The pattern of the strip conductors is obtained by a second UV lithography operation whereby the second metal layer and the first adhesive coat are etched. An insulating protective resist is deposited on the active conductive zone. The flexible film is mounted on a truncated maintaining component whereof the vertical translational and planar rotational movements are made possible by a guide supported on a spring suspension. The defective alignment between the plane of the tips and the plane of the tips and the printed circuit plane is corrected by a correcting system with three support points adjustable with screws.

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